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(54) **Title**: SCREENING PROCESS FOR MANUFACTURING A Z-DIRECTED COMPONENT FOR A PRINTED CIRCUIT BOARD

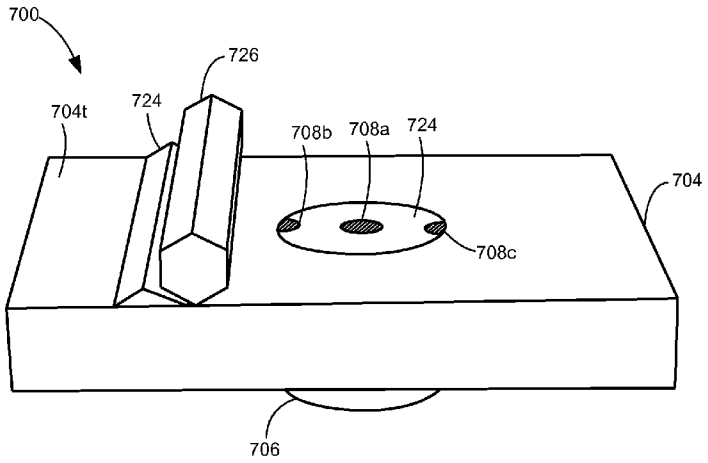


Figure 18

(57) **Abstract**: A method for manufacturing a z-directed component for insertion into a mounting hole in a printed circuit board according to one example embodiment includes adding a substrate material to a mold defining the shape of a layer of the z-directed component. A top surface of the substrate material in the mold is leveled. The substrate material in the mold is treated and the layer of the z-directed component is formed. A conductive material is applied to at least one surface of the formed layer. The z-directed component is formed that includes a stack of component layers that includes the formed layer.

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